

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TLE8886TN	**Issued**	17. May 2021
MA#	MA005411398		
Package	PG-TO220-5-12	**Weight***	2129.77 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.539	0.64	0.64	6357	6357
leadframe	inorganic material	phosphorus	7723-14-0	0.277	0.01		130	
	non noble metal	iron	7439-89-6	0.923	0.04		433	
	non noble metal	copper	7440-50-8	921.567	43.27	43.32	432709	433272
wire	non noble metal	aluminium	7429-90-5	4.066	0.19	0.19	1909	1909
encapsulation	inorganic material	zincoxide	1314-13-2	5.626	0.26		2641	
	miscellaneous	miscellaneous	-	22.502	1.06		10566	
	plastics	epoxy resin	-	84.384	3.96		39621	
	inorganic material	silicondioxide	60676-86-0	450.049	21.13	26.41	211314	264142
leadfinish	non noble metal	tin	7440-31-5	24.181	1.14	1.14	11354	11354
plating	inorganic material	phosphorus	7723-14-0	0.008			4	
	non noble metal	nickel	7440-02-0	3.285	0.15	0.15	1542	1546
solder	non noble metal	tin	7440-31-5	0.183	0.01		86	
	noble metal	silver	7440-22-4	0.228	0.01		107	
	non noble metal	lead	7439-92-1	8.715	0.41	0.43	4092	4285
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		83	
	non noble metal	iron	7439-89-6	0.590	0.03		277	
	non noble metal	copper	7440-50-8	589.466	27.68	27.72	276775	277135
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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